

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: Takashi IPPOSHI et al.

SERIAL NO: New Divisional Application

GAU: Not Yet Assigned

FILED: Herewith

EXAMINER: Not Yet Assigned

FOR: SEMICONDUCTOR DEVICE, METHOD OF MANUFACTURING THE SAME AND RESISTOR

**INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97**

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

**REFERENCES**

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references were provided in prior application serial number 09/814,116, filed March 22, 2001, now allowed, as were either statements of relevancy and any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

**RELATED CASES**

- ☐ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

**CERTIFICATION**

- ☐ Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

**DEPOSIT ACCOUNT**

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.



Gregory J. Maier

Registration No. 25,599

Customer Number

**22850**

Tel. (703) 413-3000  
Fax. (703) 413-2220  
(OSMMN 05/03)

Scott A. McKeown

Registration No. 42,866

| Form PTO 1449<br>(Modified)  |    | U.S. DEPARTMENT OF COMMERCE<br>PATENT AND TRADEMARK OFFICE   |             | ATTY DOCKET NO.<br>245112US-2DIV    |  | SERIAL NO.<br>New Divisional Application                         |                               |
|--|----|--|-------------|-------------------------------------|--|--|-------------------------------|
| LIST OF REFERENCES CITED BY APPLICANT  |    |  |             | APPLICANT<br>Takashi IPPOSHI et al. |  |  |                               |
|  |    |  |             | FILING DATE<br>Herewith             |  | GROUP<br>Not Yet Assigned  |                               |
| <b>U.S. PATENT DOCUMENTS</b>   |    |  |             |                                     |  |  |                               |
| EXAMINER<br>INITIAL  | AA | DOCUMENT<br>NUMBER   | DATE        | NAME                                | CLASS                                  | SUB<br>CLASS   | FILING DATE<br>IF APPROPRIATE |
|  | AA | 5,343,087  | 30 Aug 1994 | T. FURUYAMA                         |  |  |                               |
|  | AB | 5,698,869  | 16 Dec 1997 | M. YOSHIMI et al.                   |  |  |                               |
|  | AC | 5,838,609  | 17 Nov 198  | H. KURIYAMA                         |  |  |                               |
|  | AD | 5,801,080  | 1 Sept 1998 | Y. INOUE et al.                     |  |  |                               |
|  | AE |  |             |                                     |  |  |                               |
|  | AF |  |             |                                     |  |  |                               |
|  | AG |  |             |                                     |  |  |                               |
|  | AH |  |             |                                     |  |  |                               |
|  | AI |  |             |                                     |  |  |                               |
|  | AJ |  |             |                                     |  |  |                               |
|  | AK |  |             |                                     |  |  |                               |
|  | AL |  |             |                                     |  |  |                               |
|  | AM |  |             |                                     |  |  |                               |
|  | AN |  |             |                                     |  |  |                               |
| <b>FOREIGN PATENT DOCUMENTS</b>  |    |  |             |                                     |  |  |                               |
|  |    | DOCUMENT<br>NUMBER   | DATE        | COUNTRY                             | TRANSLATION<br>YES                  NO |  |                               |
|  | AO |  |             |                                     |  |  |                               |
|  | AP |  |             |                                     |  |  |                               |
|  | AQ |  |             |                                     |  |  |                               |
|  | AR |  |             |                                     |  |  |                               |
|  | AS |  |             |                                     |  |  |                               |
|  | AT |  |             |                                     |  |  |                               |
|  | AU |  |             |                                     |  |  |                               |
|  | AV |  |             |                                     |  |  |                               |
| <b>OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)</b>   |    |  |             |                                     |  |  |                               |
|  | AW | Hirano, Y. et al., "Bulk-Layout-Compatible 0.18.m SOI-CMOS Technology Using Body-Fixed Partial Trench Isolation (PTI)," <u>IEEE International SOI Conference</u> , Oct. 1999, pp. 131.132. |             |                                     |  |  |                               |
|  | AX |  |             |                                     |  |  |                               |
|  | AY |  |             |                                     |  |  |                               |
|  | AZ |  |             |                                     |  | <input type="checkbox"/> Additional References sheet(s) attached |                               |
| Examiner   |    |  |             |                                     | Date Considered                        |  |                               |
| *Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. |    |  |             |                                     |  |  |                               |